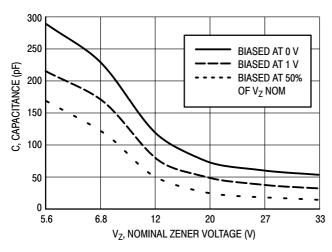
ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted) UNIDIRECTIONAL

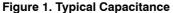
(Circuit tied to pins 1, 2, and 5; Pins 2, 3, and 5; Pins 2, 4, and 5; or Pins 2, 5, and 6) ($V_F = 0.9 \text{ V Max} \otimes I_F = 10 \text{ mA}$)

	Breakdown Voltage				Max Reverse Leakage Current			Max	Max Reverse Voltage @ I _{RSM}	Maximum	Capacitance @ 0 Volt Bias, 1 MHz	
		V _{ZT} (Note 5) (V)		@ I _{ZT}	I _R	V _R	Max Zener Impedance (Note 7)	Reverse Surge Current	(Note 6) (Clamping Voltage)	Temperature Coefficient of V _Z	(pF)	
Device	Min	Nom	Max	(mA)	(nA)	(V)	Z _{ZT} @ I _{ZT} (Ω) (mA)	I _{RSM} (A)	V _{RSM} (V)	(mV/°C)	Min	Max
MMQA5V6T1,T3	5.32	5.6	5.88	1.0	2000	3.0	400	3.0	8.0	1.26	-	-
MMQA6V2T1,T3	5.89	6.2	6.51	1.0	700	4.0	300	2.66	9.0	10.6	-	-
MMQA6V8T1,T3	6.46	6.8	7.14	1.0	500	4.3	300	2.45	9.8	10.9	100	250
MMQA12VT1,T3	11.4	12	12.6	1.0	75	9.1	80	1.39	17.3	14	-	-
MMQA13VT1	12.4	13	13.7	1.0	75	9.8	80	1.29	18.6	15	-	-
MMQA15VT1,T3	14.3	15	15.8	1.0	75	11	80	1.1	21.7	16	-	-
MMQA18VT1,T3	17.1	18	18.9	1.0	75	14	80	0.923	26	19	-	-
MMQA20VT1,T3	19	20	21	1.0	75	15	80	0.84	28.6	20.1	-	-
MMQA21VT1,T3	20	21	22.1	1.0	75	16	80	0.792	30.3	21	-	-
MMQA22VT1,T3	20.9	22	23.1	1.0	75	17	80	0.758	31.7	22	-	-
MMQA24VT1,T3	22.8	24	25.2	1.0	75	18	100	0.694	34.6	25	-	-
MMQA27VT1,T3	25.7	27	28.4	1.0	75	21	125	0.615	39	28	-	-
MMQA33VT1,T3	31.4	33	34.7	1.0	75	25	200	0.504	48.6	37	-	-

- 1. Non-repetitive current pulse per Figure 5 and derate above $T_A = 25^{\circ}C$ per Figure 4.
- 2. Non-repetitive current pulse per Figure 6 and derate above $T_A = 25$ °C per Figure 4.
- 3. FR-5 = $1.0 \times 0.75 \times 0.62$ in.
- 4. Alumina = 0.4 x 0.3 x 0.024 in., 99.5% alumina
- 5. V_Z measured at pulse test current I_T at an ambient temperature of 25°C.
 6. Surge current waveform per Figure 5 and derate per Figure 4.
- 7. Z_{ZT} is measured by dividing the AC voltage drop across the device by the AC current supplied. The specified limits are $I_{Z(AC)} = 0.1 I_{Z(DC)}$, with AC frequency = 1 kHz.

TYPICAL CHARACTERISTICS





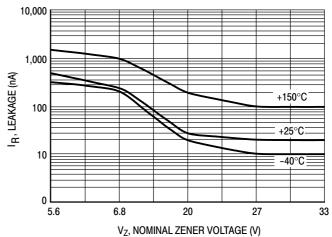
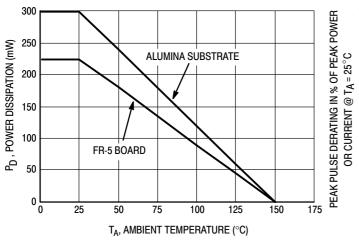


Figure 2. Typical Leakage Current

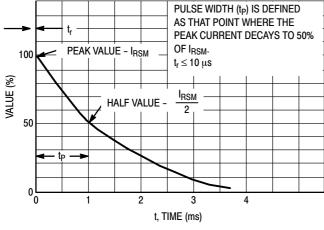
TYPICAL CHARACTERISTICS



100 90 80 70 60 50 30 20 10 25 75 100 125 150 175 200 TA, AMBIENT TEMPERATURE (°C)

Figure 3. Steady State Power Derating Curve

Figure 4. Pulse Derating Curve



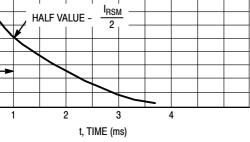


Figure 5. $10 \times 1000 \mu s$ Pulse Waveform

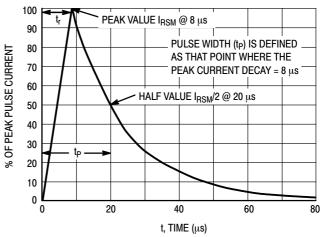


Figure 6. $8 \times 20 \mu s$ Pulse Waveform

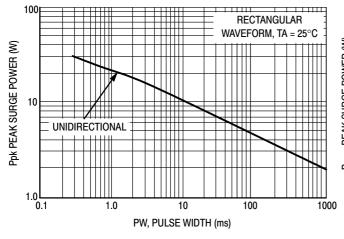


Figure 7. Maximum Non-Repetitive Surge Power, Ppk versus PW

Power is defined as $V_{RSM} \times I_{Z}(pk)$ where V_{RSM} is the clamping voltage at I₇(pk).

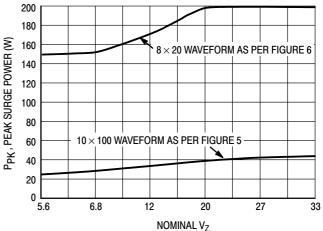


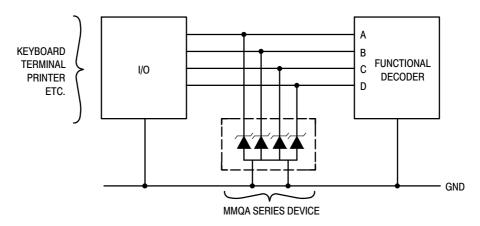
Figure 8. Typical Maximum Non-Repetitive Surge Power, Ppk versus VBR

TYPICAL COMMON ANODE APPLICATIONS

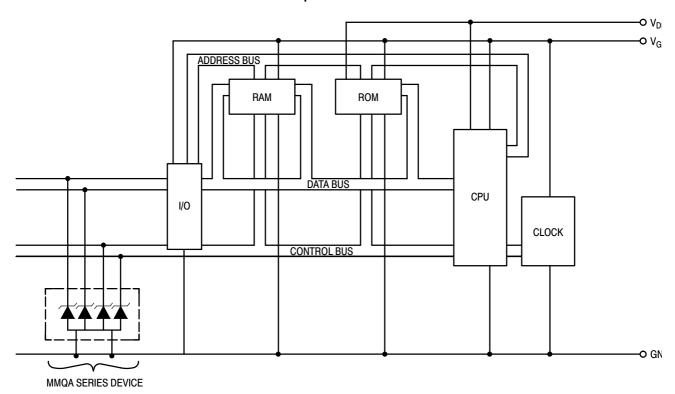
A quad junction common anode design in a SC-74 package protects four separate lines using only one package. This adds flexibility and creativity to PCB design especially

when board space is at a premium. A simplified example of MMQA Series Device applications is illustrated below.

Computer Interface Protection



Microprocessor Protection



DEVICE MARKING AND ORDERING INFORMATION

Device*	Device Marking	Package	Shipping [†]
MMQA5V6T1*	5A6	SC-74	3,000/Tape & Reel
MMQA6V2T1*	6A2	SC-74	3,000/Tape & Reel
MMQA6V2T3*	6A2	SC-74	10,000/Tape & Reel
MMQA6V8T1*	6A8	SC-74	3,000/Tape & Reel
MMQA12VT1*	12A	SC-74	3,000/Tape & Reel
MMQA13VT1*	13A	SC-74	3,000/Tape & Reel
MMQA15VT1*	15A	SC-74	3,000/Tape & Reel
MMQA18VT1*	18A	SC-74	3,000/Tape & Reel
MMQA20VT1*	20A	SC-74	3,000/Tape & Reel
MMQA20VT3*	20A	SC-74	10,000/Tape & Reel
MMQA21VT1*	21A	SC-74	3,000/Tape & Reel
MMQA22VT1*	22A	SC-74	3,000/Tape & Reel
MMQA24VT1*	24A	SC-74	3,000/Tape & Reel
MMQA27VT1*	27A	SC-74	3,000/Tape & Reel
MMQA27VT3*	27A	SC-74	10,000/Tape & Reel
MMQA33VT1*	33A	SC-74	3,000/Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Mechanical Characteristics:

CASE: Void-free, transfer-molded, thermosetting plastic case.

FINISH: Corrosion resistant finish, easily solderable.

Package designed for optimal automated board assembly.

Small package size for high density applications.

Available in 8 mm Tape and Reel.

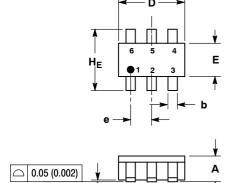
Use the Device Number to order the 7 inch/3,000 unit reel.

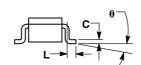
Replace the "T1" with "T3" in the Device Number to order the 13 inch/10,000 unit reel.

^{*}The "G" suffix indicates Pb-Free package available.

PACKAGE DIMENSIONS

SC-74 CASE 318F-05 ISSUE M





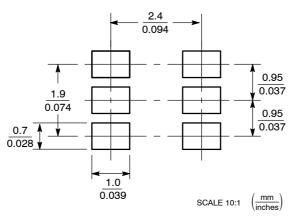
- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH
 THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM
- THICKNESS OF BASE MATERIAL. 318F-01, -02, -03, -04 OBSOLETE. NEW STANDARD 318F-05.

	M	ILLIMETE	RS	INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.90	1.00	1.10	0.035	0.039	0.043	
A1	0.01	0.06	0.10	0.001	0.002	0.004	
b	0.25	0.37	0.50	0.010	0.015	0.020	
С	0.10	0.18	0.26	0.004	0.007	0.010	
D	2.90	3.00	3.10	0.114	0.118	0.122	
E	1.30	1.50	1.70	0.051	0.059	0.067	
е	0.85	0.95	1.05	0.034	0.037	0.041	
L	0.20	0.40	0.60	0.008	0.016	0.024	
HE	2.50	2.75	3.00	0.099	0.108	0.118	
θ	0°	_	10°	0°	_	10°	

- STYLE 1: PIN 1. CATHODE

 - 2. ANODE 3. CATHODE 4. CATHODE
 - 5. ANODE
 - CATHODE

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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